

Tra-Con Tra-Bond FS291 Thixotropic Room Temperature Cure Epoxy Adhesive

Category: Polymer, Adhesive, Thermoset, Epoxy

Material Notes:

TRA-BOND FS291 is a thixotropic room temperature cure epoxy adhesive system developed for structural bonding applications on vertical or overhead surfaces where its no-sag characteristics are critical. This medium exotherming system exhibits excellent flow and wetting characteristics for precisely located dispensing from static mixing cartridges. Fully cured TRA-BOND FS291 may be employed on a wide variety of substrates including glass, most metals, and variety of plastics and provides excellent resistance to salt solutions, mild acids and alkalis, and many other chemicals including petroleum solvents, lubricating oils, and alcohol.Information provided by Tra-Con Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Tra-Con-Tra-Bond-FS291-Thixotropic-Room-Temperature-Cure-Epoxy-Adhesive.php

Physical Properties	Metric	English	Comments
Solids Content	100 %	100 %	Reactive Solids Content

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	80	80	
Adhesive Bond Strength	22.8 MPa	3300 psi	Lap shear, alum to alum

Electrical Properties	Metric	English	Comments
Volume Resistivity	2.70e+13 ohm-cm	2.70e+13 ohm-cm	

Processing Properties	Metric	English	Comments
Cure Time	60.0 min	1.00 hour	
Cure rime	@Temperature 65.0 °C	@Temperature 149 °F	
	1440 min	24.0 hour	
	@Temperature 25.0 °C	@Temperature 77.0 °F	

Descriptive Properties	Value	Comments
Mix Ratio, parts by weight	100/81	Resin/Hardener

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